

Title (en)  
Light emitting diode package structures

Title (de)  
Lichtemissionsdiodenpaketstrukturen

Title (fr)  
Structures de paquets à diodes électroluminescentes

Publication  
**EP 2911209 A1 20150826 (EN)**

Application  
**EP 15156165 A 20150223**

Priority  
• CN 201420075500 U 20140221  
• US 201462004622 P 20140529

Abstract (en)  
A light emitting diode package, comprising: a substrate including an upper surface and a lower surface, the substrate comprising a metal block and an electrically insulating region surrounding, at least in part, the metal block; and a light emitting diode chip mounted on the substrate, the light emitting diode chip in electrical communication with the metal block; and an encapsulant covering at least an upper surface of the light emitting diode chip.

IPC 8 full level  
**H01L 33/64** (2010.01); **H01L 25/075** (2006.01)

CPC (source: EP US)  
**H01L 25/0753** (2013.01 - EP US); **H01L 33/54** (2013.01 - US); **H01L 33/647** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US)

Citation (search report)  
• [X] US 2008012036 A1 20080117 - LOH BAN P [US], et al  
• [X] US 8236584 B1 20120807 - CHEM CHYI SHYUAN [TW], et al  
• [X] US 2006102922 A1 20060518 - WU CHING-YI [TW], et al

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 2911209 A1 20150826**; CN 203707181 U 20140709; TW M485515 U 20140901; US 2015372211 A1 20151224

DOCDB simple family (application)  
**EP 15156165 A 20150223**; CN 201420075500 U 20140221; TW 103210362 U 20140612; US 201514628197 A 20150220